

## **Wide Input Range CC/CV Step Down** **Controller**

### **❖ GENERAL DESCRIPTION**

The AX3077 is a step down PWM controller with a driving dual output current to 9.6A (4.8A+4.8A). It is designed to allow for operating a wide supply voltage range from 8V to 40V. The external shutdown function can be controlled by logic level to pull COMP pin down, and then comes into standby mode. The external compensation makes feedback control have good line and load regulation with flexible external design.

The AX3077 operates in the CC(Constant output Current) mode or CV(Constant output Voltage) mode, and the OCP current value is set by current sensing resistors.

The AX3077 is suitable for the DC/DC switching power applications when requested the current limit function. The devices are available in MSOP-10L-EP and TDFN-10L(3\*3) packages and require very few external devices for operation.

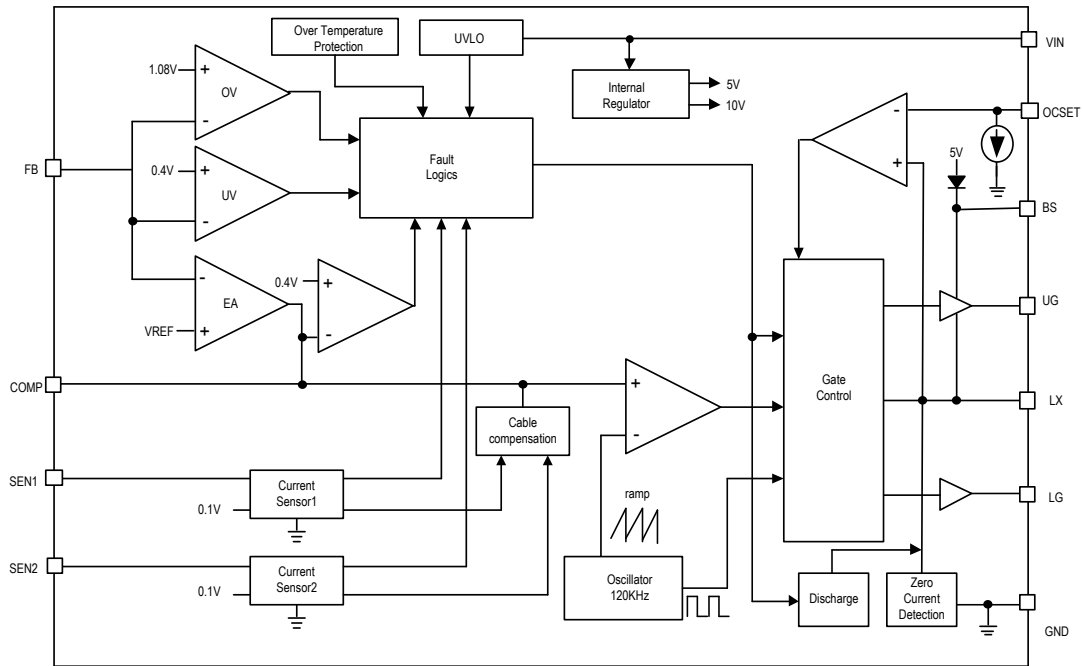
### **❖ FEATURES**

- $V_{IN}$  Operate with 8.0V ~ 40V Supply Voltage
- $V_{OUT}$  Accuracy ( $V_{FB} = 1.0V$ )  $\pm 2.0\%$
- Dual-Channeling CC/CV Mode Control
- External Current Limit Setting for 2 channel
- Thermal, Over voltage and Short Circuit Protection
- Internal Soft Start ~ 3ms
- Fixed Frequency 120kHz
- UVLO Protection (min=7V, typ=7.5V, max=8V)
- Duty Cycle Range (0~93%)
- Single Pin to External Compensation and Shutdown Control
- Built in Adjustable Cable-Compensation
- MSOP-10L-EP and TDFN-10L(3\*3) Package
- RoHS and Halogen free compliance

### **❖ APPLICATION**

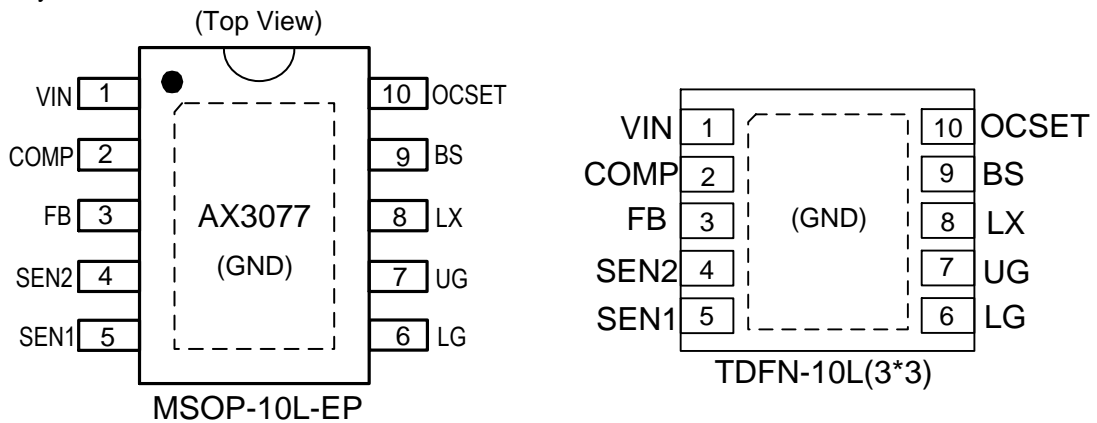
- Car Charger
- High-Brightness Lighting
- Portable Charger Devices
- General-Purpose DC/DC Controller with Current Limit

❖ BLOCK DIAGRAM



❖ PIN ASSIGNMENT

The package of AX3077 are MSOP-10L-EP and TDFN-10L(3\*3) the pin assignment is given by:



Name	Description
VIN	Power Supply Input. Bypass this pin with a 2.2uF ceramic capacitor to GND, placed as close to the IC as possible.
COMP	Error Amplifier Output. This is the output of the error amplifier (EA) and the non-inverting input of the PWM comparator. Use this pin in combination with the FB pin to compensate the voltage control feedback loop of the converter. Pulling COMP to a level below 0.4V nominal disables the controller, causes the oscillator to stop, and makes the UG and LG outputs held low.
FB	Feedback Pin. The voltage at this pin is regulated to 1.0V. Connect to the resistor divider between output and GND to set the output voltage.
SEN2	The Current Sense Input2 Pin. When the SEN2 is larger than the current sense voltage, OCP function will enable.
SEN1	The Current Sense Input1 Pin. When the SEN1 is larger than the current sense voltage, OCP function will enable.
GND	Ground. Connect this pin to a large PCB copper area for best heat dissipation, Return FB, and COMP to this GND and connect this GND to power GND at a single point for best noise immunity.
LG	Output to Low-side Gate Driver.
UG	Output to High-side Gate Driver.
LX	Power Switching Output to External Inductor.
BS	Bootstrap Pin. This provides power to the internal higher MOSFET gate driver. Connect a 100nF capacitor from BS pin to LX pin.
OCSET	Setting of Over-Current limit threshold (High-side MOS Current detect)

❖ ORDER/MARKING INFORMATION

Order Information	
<p><b>AX3077 XXX X</b></p> <p>Package Type                      Packing</p> <p>EU: MSOP-10L-EP                  Blank: Tube</p> <p>J10: TDFN-10L(3*3)                A: Taping</p>	
Top Marking(MSOP-10L-EP)	Top Marking(TDFN-10L(3*3))
<p>Logo ← <b>AX</b> 3 0 7 7 → Part number</p> <p>    Y Y W W X → ID code: internal</p> <p>            WW: 01~52</p> <p>                    Year: 18=2018</p> <p>                            19=2019</p> <p>                            20=2020</p> <p>                            21=2021</p> <p>                            22=2022</p> <p>                            ⋮</p> <p>                            45=2045</p>	<p>    3 0 7 7 → Part number</p> <p>    Y Y W W X → ID code: internal</p> <p>            WW: 01~52</p> <p>                    Year: 18=2018</p> <p>                            19=2019</p> <p>                            20=2020</p> <p>                            21=2021</p> <p>                            22=2022</p> <p>                            ⋮</p> <p>                            45=2045</p>

**❖ ABSOLUTE MAXIMUM RATINGS** (at  $T_A = 25^\circ\text{C}$ )

Characteristics		Symbol	Rating	Unit
Supply Input Voltage, OCSET		$V_{IN}$	-0.3 to +43	V
BS to LX			-0.3 to +7	V
LX to GND			-1 to $+V_{IN}+1$	V
BS, UG to GND			$V_{LX}-0.3$ to $V_{LX}+7$	V
FB, COMP, SEN1, SEN2 to GND			0.3 to +7	V
LG to GND			14	V
ESD HBM (Human Body Mode)			$\pm 2\text{K}$	V
ESD MM (Machine Mode)			$\pm 200$	V
Power Dissipation, $P_D$ @ $T_A=25^\circ\text{C}$		$P_D$	$(T_J-T_A) / \theta_{JA}$	W
Thermal Resistance from Junction to case	MSOP-10L-EP	$\theta_{JC}$	30	$^\circ\text{C/W}$
	TDFN-10L(3*3)		7.8	
Thermal Resistance from Junction to ambient	MSOP-10L-EP	$\theta_{JA}$	86	$^\circ\text{C/W}$
	TDFN-10L(3*3)		68	

**❖ RECOMMENDED OPERATION CONDITIONS**

Characteristics		Symbol	Rating	Unit
Storage Temperature Range		$T_{ST}$	-65 to +150	$^\circ\text{C}$
Junction Temperature		$T_J$	-40 to +125	$^\circ\text{C}$
Operating Temperature		$T_{OP}$	-40 to +85	$^\circ\text{C}$
Lead Temperature Range(Soldering 10sec)			260	$^\circ\text{C}$

Note 1: Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device.

These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2: Devices are ESD sensitive. Handling precaution recommended.

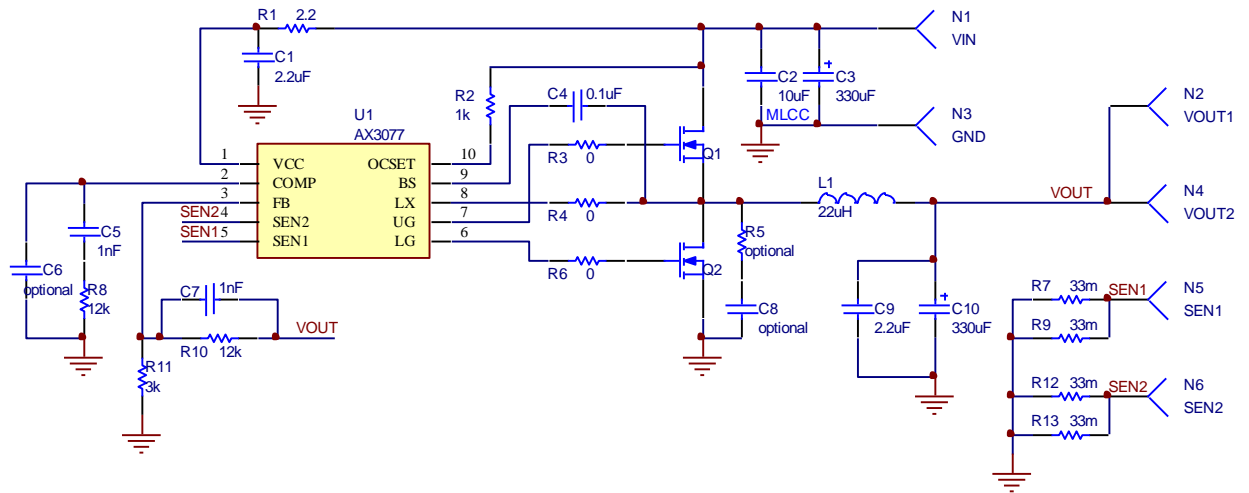
Note 3:  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^\circ\text{C}$  on a high effective thermal conductivity test board of JEDEC 51-7 thermal measurement standard.

**❖ ELECTRICAL CHARACTERISTICS**
 $V_{IN}=12V$ ,  $T_A=25^{\circ}C$  (unless otherwise specified.) Mosfet use AMD4004\*2.

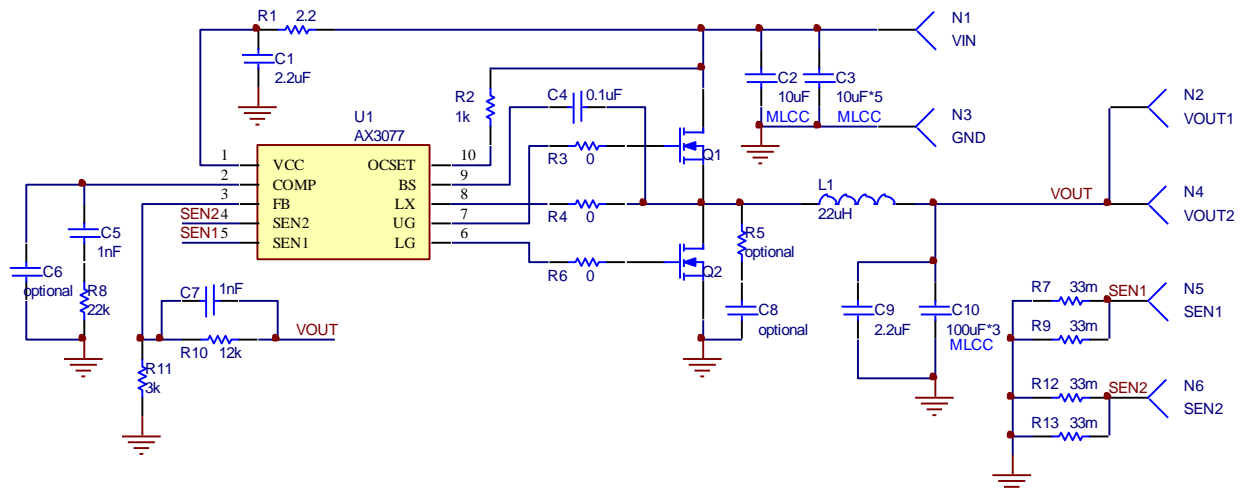
Characteristics	Symbol	Test Conditions	Min	Typ	Max	Units
Supply Voltage Range $V_{IN}$	$V_{IN}$		8	-	40	V
Supply Input Current	$I_{CCQ}$	COMP/EN=GND	-	800	-	$\mu A$
	$I_{CC}$	12Vin to 5Vout, No load	-	1.4	-	mA
	$I_{CC}$	30Vin to 5Vout, No load	-	1.4	-	mA
<b>Power-On-Reset</b>						
VIN POR Threshold	$V_{INRTH}$	$V_{IN}$ Rising.	7	7.5	8	V
	$V_{INFTH}$	$V_{IN}$ Falling.	6	6.5	7	
<b>Oscillator</b>						
Normal PWM Frequency	$F_{OSC}$	$I_{OUT}=200mA$	96	120	144	kHz
Minimum On-Time	$T_{ON-MIN}$		-	200	-	ns
Duty Cycle Range	Duty		0	-	90	%
<b>Reference</b>						
Reference Voltage	$V_{FB}$		-	1.0	-	V
Reference Voltage Tolerance			-2	-	+2	%
Cable compensation Current	$I_{FB}$	$V_{SEN1}$ Or $V_{SEN2} = 100mV$	4.25	5	5.75	$\mu A$
<b>PWM Error Amplifier</b>						
COMP Shutdown Threshold Voltage			-	0.4	-	V
COMP Source Current		$V_{COMP}=V_{COMP\_H}-1V$	-	200	-	$\mu A$
COMP Sink Current		$V_{COMP}=1V$	-	200	-	$\mu A$
<b>Current Sense Amplifier</b>						
SEN1/SEN2 OCP Threshold	$V_{SEN}$		95	100	105	mV
<b>Secondary High-Side(Q1) Peak Current limit</b>						
OCSET Current Sink	$I_{OCSET}$	$R_{SEN}=0m\Omega$ , NO CC	160	200	240	$\mu A$
<b>Pre-Driver (Ensured by design)</b>						
UG Driver	source	$V_{UG}=1V$ ; $V_{BS}-V_{LX}=5V$	-	0.7	-	A
	sink	$V_{UG}-V_{LX}=1V$ ; $V_{BS}-V_{LX}=5V$	-	1.3	-	$\Omega$
LG Driver	source	$V_{LG}=1V$ ; $V_{CC}=12V$	-	1.4	-	A
	sink	$V_{UG}-GND=1V$ ; $V_{CC}=12V$	-	0.7	-	$\Omega$
Dead Time		UG low to LG high	-	35	-	nS
		LG low to UG high	-	35	-	nS
<b>Protection</b>						
Over Temperature Shutdown			-	160	-	$^{\circ}C$
Over Temperature Hysteresis			-	40	-	$^{\circ}C$
<b>Soft Start</b>						
Soft Start Time	$T_{SS}$		-	3	-	ms
Recycle Time			-	0.5	-	s
<b>Output Short Circuit Protect Section</b>						
Short Circuit Fold Back Voltage	$V_{SCP}$		-	0.4	-	V

## ❖ APPLICATION CIRCUIT

### Cout=E-cap



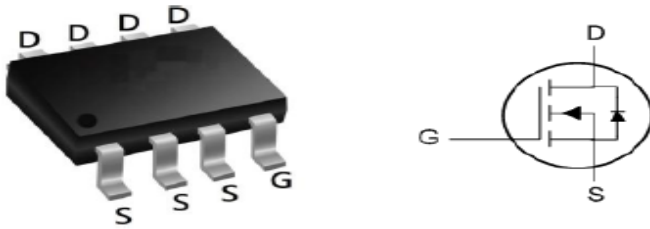
### Cout=MLCC cap



**❖ MOSFET SUGGESTION**

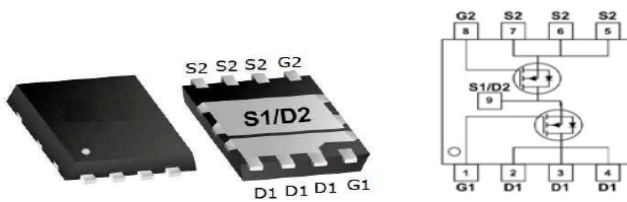
AMS4004\*2 for 4.8A

BVDSS	RDSON	ID
40V	12mΩ	8.5A

**SOP8 Pin configuration**


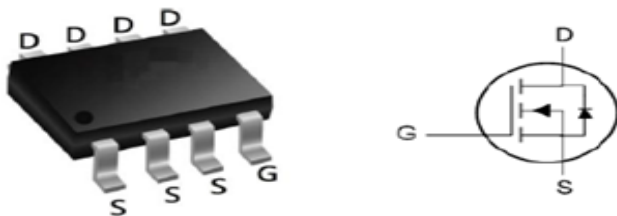
AMBA4810 for 4.8A~6A → 2.4A+2.4A or 2A+2A+2A or 6A

BVDSS	RDSON	ID
40V	17mΩ	39A
40V	8.5mΩ	54A

**PRPAK5X6 Pin configuration**


AMS4006\*2 for 6A~8A → 2A+2A+2A or 2A+2A+2A+2A or 8A

BVDSS	RDSON	ID
40V	7.5 mΩ	10.5 A

**SOP8 Pin configuration**


❖ FUNCTION DESCRIPTIONS

**CC/CV Mode Control**

The AX3077 provides CC/CV function. The Constant output Current control Mode and Constant output Voltage control Mode.

**Over Current Protection**

The AX3077 provides over current protection. A drop voltage on the current sensing resistor is over the OCP value, the OCP function will shut down the controller.

**Soft Start**

The AX3077 has internal soft start function to control rise rate of the output voltage and limits the large inrush current at start up. The typical soft start interval is about 3mS.

**Power on Reset**

A power-on reset circuit monitors the input voltage. When the input voltage exceeds 7.5V, the converter will start operation. Once input voltage falls below 6.5V, the controller will shut down.

**Over Temperature Protection**

The AX3077 provides over temperature protection. The OTP will shut down the converter when junction temperature exceeds 160°C. Once the junction temperature cools down by approximately 40°C, the converter will resume normal operation.

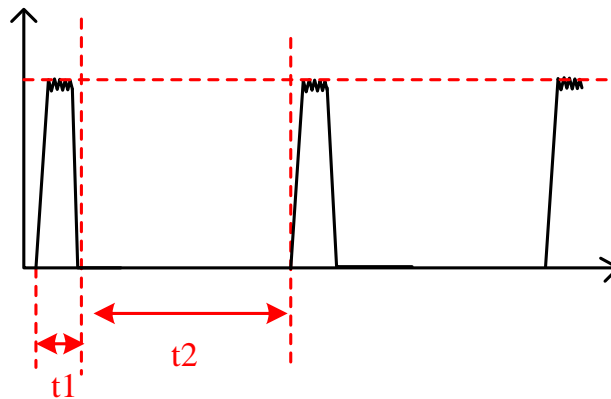
**Current Limit Protection**

The Current limit is set by outside resistance (R<sub>SENSE</sub>), When the SEN1 or SEN2 voltage larger than 100mV, the current limit is happened that driver can be turned off. The current limit set according to the following equation:

$$\text{Current Limit (A)} = \frac{100\text{mV}}{R_{\text{SENSE}}}$$

**Output Short-Circuit Protection**

The AX3077 provides output short-circuit protection function. When V<sub>OUT</sub> is short (V<sub>FB</sub><0.4V), the auto restart function can be started that restart the regulator cycle by cycle. The cycle time is set by internal counter.



t1 = 18m(Sec.)

t2 = 550m(Sec.)



**Over Voltage Protection**

The AX3077 monitor FB Voltage to detect over voltage. The over voltage feature minimizes output overshoot by turning off high-side(Q1)/low-side(Q2) MOSFET and turning on discharge circuit (100mA) when FB voltage reaches to the rising OVP threshold which is nominally 108% of the internal voltage reference.

**Output Cable Resistance Compensation**

To compensate for resistive voltage drop across the charger's output cable, the AX3077 integrates a simple, user-programmable cable voltage drop compensation using the impedance at the FB pin. Use the curve in Figure 2 to choose the proper feedback resistance values for cable compensation. R<sub>FB1</sub> is the high side resistor of voltage divider.

The Vsen1 or Vsen2 take the big one.

$$V_{OUT} = [(1 + \frac{R_{FB1}}{R_{FB2}}) \times V_{FB}] + [R_{FB1} \times (\frac{V_{SEN}}{18K} - 0.55uA)]$$

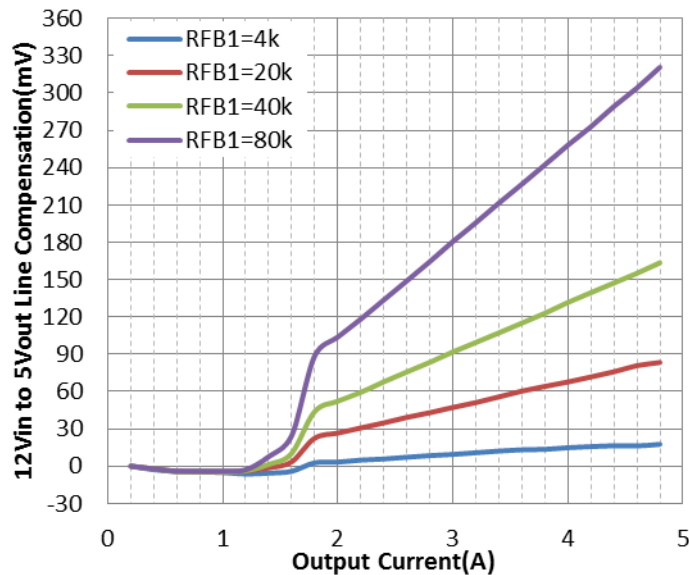


Figure2 12Vin to 5Vout Cable Compensation (R<sub>SEN</sub>=18mΩ)

**High Side MOSFET (Q1) Peak Current Limit**

A resistor (R<sub>OCSET</sub>) connect from OCSET pin to the drain of the high side MOSFET (Q1), An 250ns blanking time is used to avoid the current sampling error due to turn on switching noise.

OCP function monitors the High-Side MOSFET (Q1) voltage and the OCSET pin to set the over-current trigger threshold, The Q1 Peak Current Limit (I<sub>Q1\_OCP</sub>) value can be calculated through:

$$I_{Q1\_OCP} = \frac{I_{OCSET} * R_{OCSET}}{R_{ON}(Q1)}$$

❖ APPLICATION INFORMATION

Output Voltage Setting

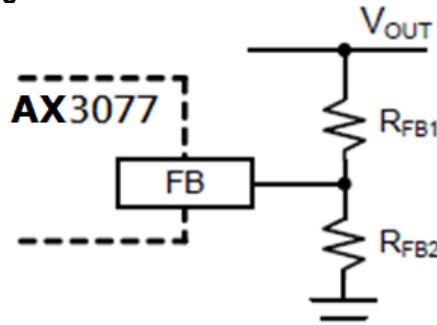


Figure1 Output Voltage Setting

Figure 1 shows the connections for setting the output voltage. Select the proper ratio of the two feedback resistors  $R_{FB1}$  and  $R_{FB2}$  based on the output voltage. Typically, use  $R_{FB2} \approx 1k\Omega$  and determine  $R_{FB1}$  from the following equation:

$$R_{FB1} = R_{FB2} \left( \frac{V_{OUT}}{V_{FB}} - 1 \right)$$

Inductor Selection

The inductor maintains a continuous current to the output load. This inductor current has a ripple that is dependent on the inductance value:

Higher inductance reduces the peak-to-peak ripple current. The tradeoff for high inductance value is the increase in inductor core size and series resistance, and the reduction in current handling capability. In general, select an inductance value L based on ripple current requirement:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} f_{LX} I_{OUTMAX} K_{RIPPLE}}$$

where  $V_{IN}$  is the input voltage,  $V_{OUT}$  is the output voltage,  $f_{LX}$  is the switching frequency,  $I_{OUTMAX}$  is the maximum output current, and  $K_{RIPPLE}$  is the ripple factor. Typically, choose  $K_{RIPPLE} = 30\%$  to correspond to the peak-to-peak ripple current being 30% of the maximum output current.

With this inductor value, the peak inductor current is  $I_{OUT} \times (1 + K_{RIPPLE}/2)$ . Make sure that this peak inductor current is less than the controller's current limit. Finally, select the inductor core size so that it does not saturate at the peak inductor current.

Input Capacitor

The input capacitor needs to be carefully selected to maintain sufficiently low ripple at the supply input of the converter. A low ESR capacitor is highly recommended. Since large current flows in and out of this capacitor during switching, its ESR also affects efficiency.

The input capacitance needs to be higher than 100 $\mu$ F. The best choice is the ceramic type, however, low ESR tantalum or electrolytic types may also be used provided that the RMS ripple current rating is higher than 50% of the output current. The input capacitor should be placed close to the  $V_{IN}$  and GND pins of the IC, with the shortest traces possible. In the case of tantalum or electrolytic types, they can be further away if a small parallel 1 $\mu$ F ceramic capacitor is placed right next to the IC. Especially C8 capacitor should be placed as close as possible to the  $V_{IN}$  pin.

### Output Capacitor

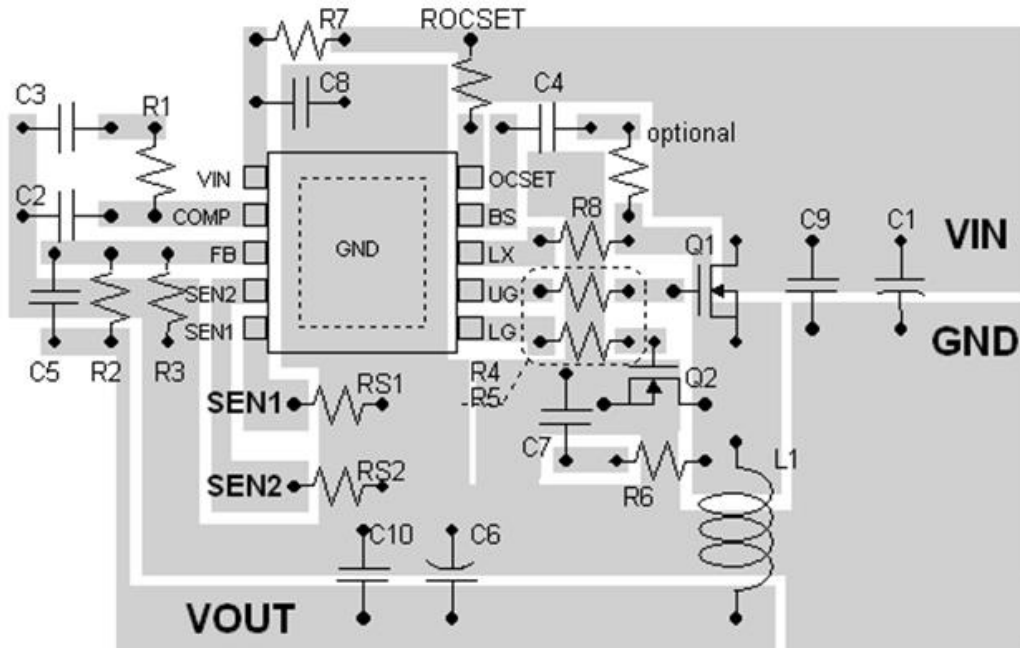
The output capacitor also needs to have low ESR to keep low output voltage ripple. The output ripple voltage is:

$$V_{\text{RIPPLE}} = I_{\text{OUTMAX}} K_{\text{RIPPLE}} R_{\text{ESR}} + \frac{V_{\text{IN}}}{28 \times f_{\text{LX}}^2 LC_{\text{OUT}}}$$

where  $I_{\text{OUTMAX}}$  is the maximum output current,  $K_{\text{RIPPLE}}$  is the ripple factor,  $R_{\text{ESR}}$  is the ESR of the output capacitor,  $f_{\text{LX}}$  is the switching frequency,  $L$  is the inductor value, and  $C_{\text{OUT}}$  is the output capacitance. In the case of ceramic output capacitors,  $R_{\text{ESR}}$  is very small and does not contribute to the ripple. Therefore, a lower capacitance value can be used for ceramic type. In the case of tantalum or electrolytic capacitors, the ripple is dominated by  $R_{\text{ESR}}$  multiplied by the ripple current. In that case, the output capacitor is chosen to have sufficiently low ESR.

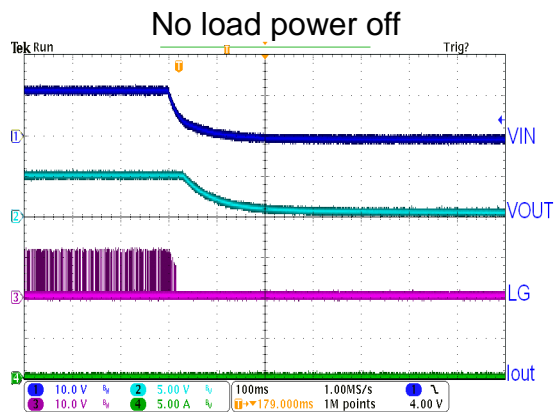
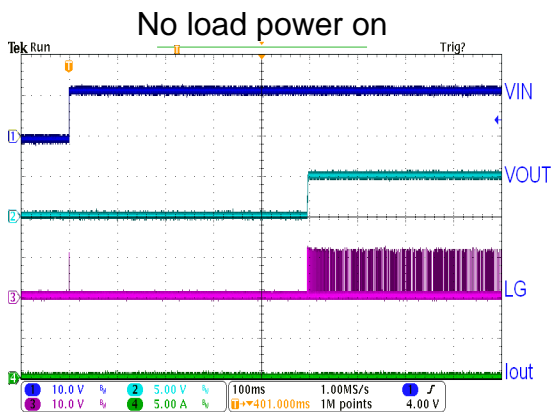
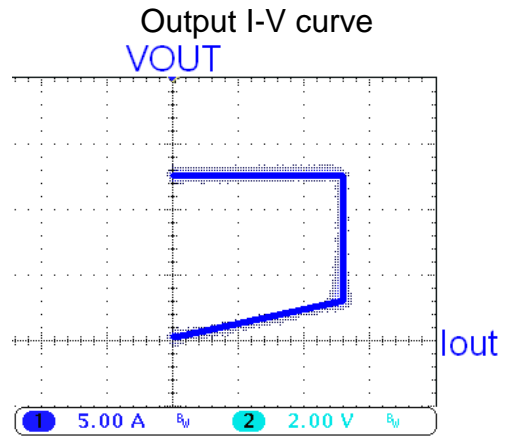
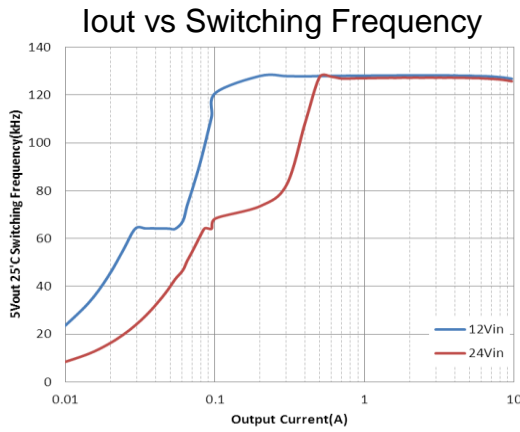
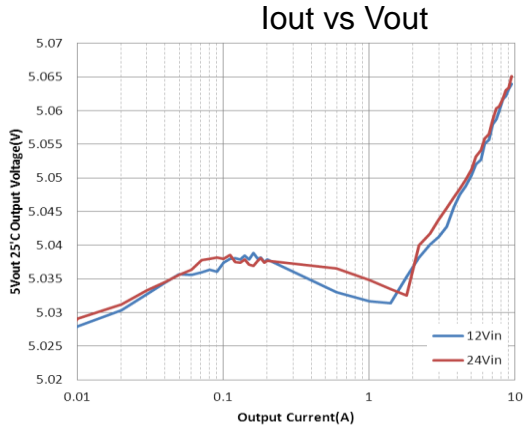
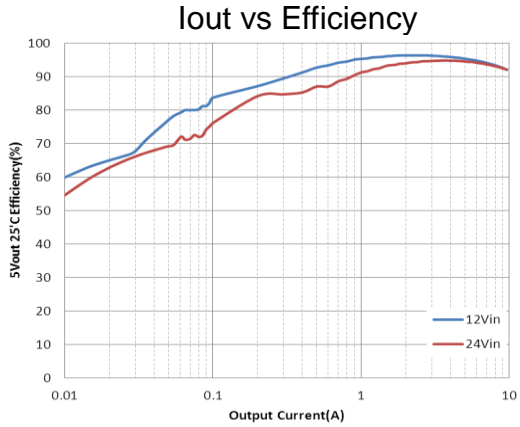
For ceramic output capacitor, typically choose a capacitance of about 470μF. For tantalum or electrolytic capacitors, choose a capacitor with less than 50mΩ ESR.

### PCB Layout Recommendations

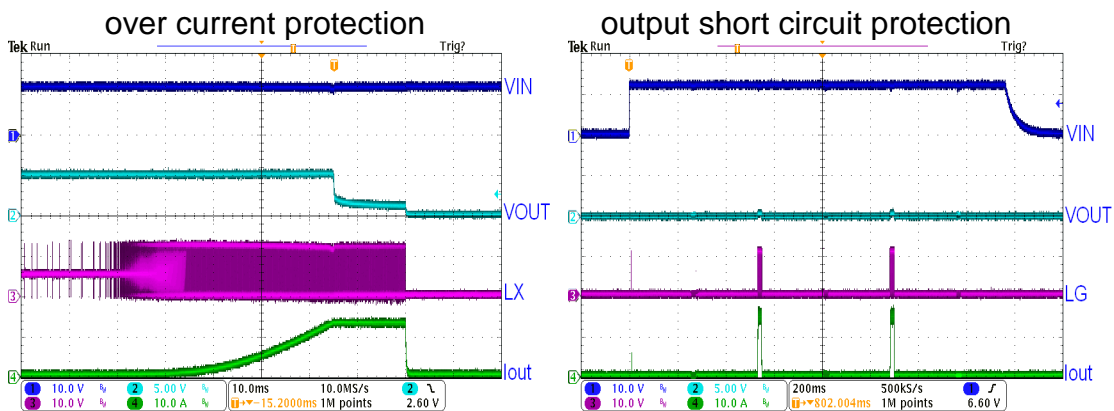
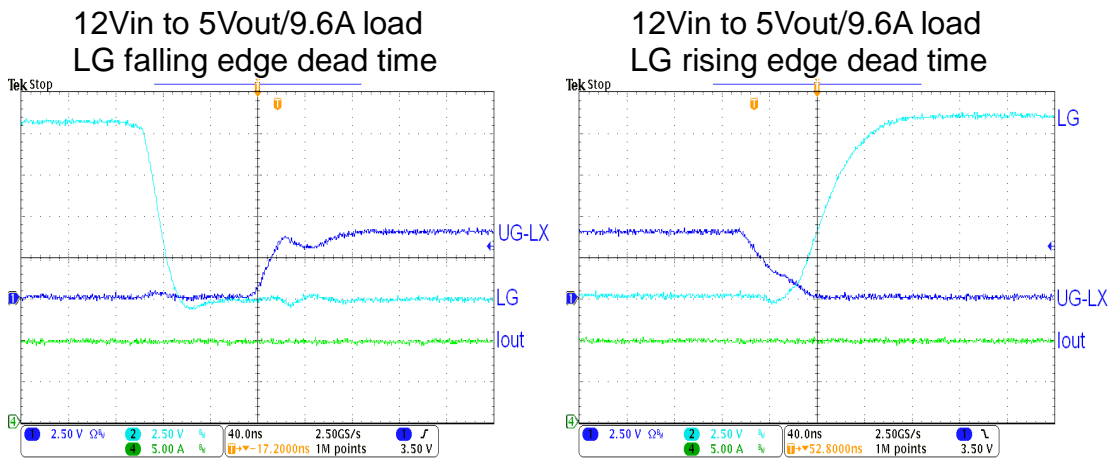
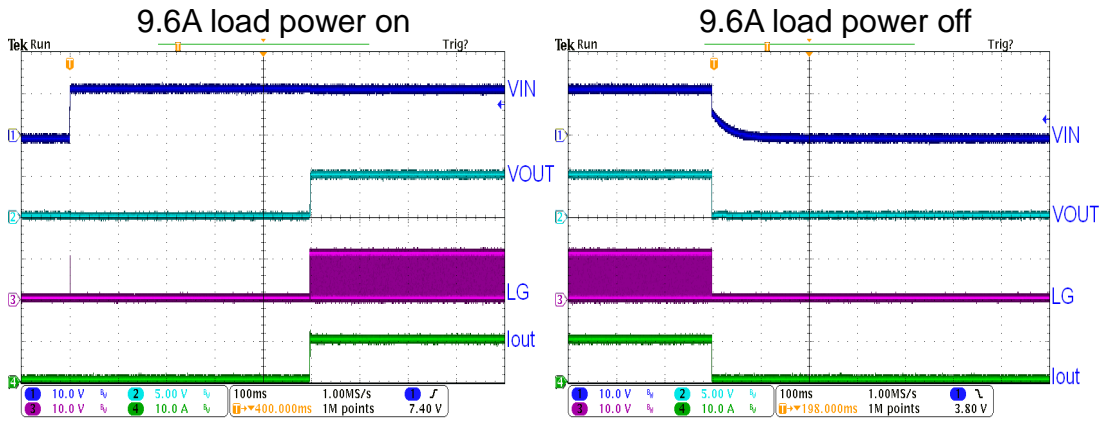


1. PCB trace defined as LX node, which connects to source of switching MOSFET, drain of rectifying MOSFET and high-voltage side of the inductor, should be as short and wide as possible.
2. All sensitive analog traces such as SEN1, SEN2, COMP and FB should place away from high-voltage switching nodes such as LX, UG or LG nodes to avoid coupling.
3. C8 input bypass capacitor should be placed to the VIN pin as close as possible.
4. Connections from the drivers to the respective gate of the high-side or the low-side MOSFET should be as short as possible to reduce stray inductance. Use a 0.65 mm (25 mils) or wider trace.
5. Gather the ground terminals of the  $V_{\text{IN}}$  capacitor(s),  $V_{\text{OUT}}$  capacitor(s), and the source of the low-side MOSFETs as close as possible. Signal ground and power ground should be connected strongly together near the device.

❖ TYPICAL CHARACTERISTICS

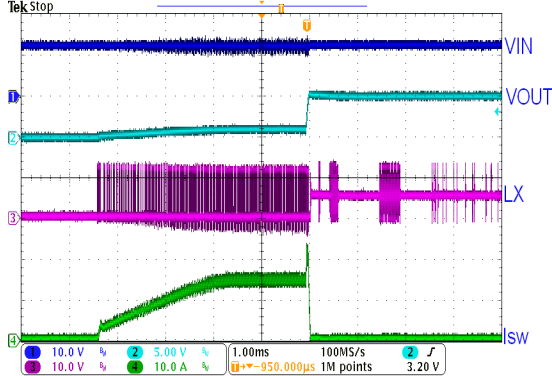


❖ TYPICAL CHARACTERISTICS (CONTINUOUS)

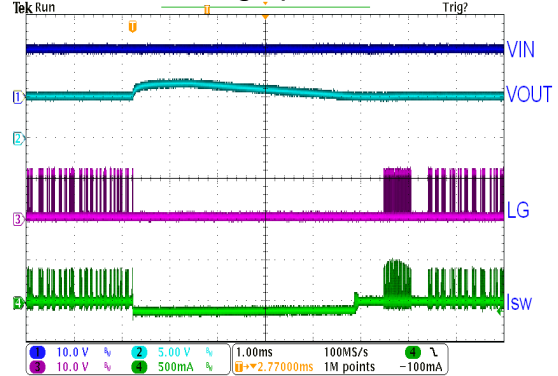


❖ TYPICAL CHARACTERISTICS (CONTINUOUS)

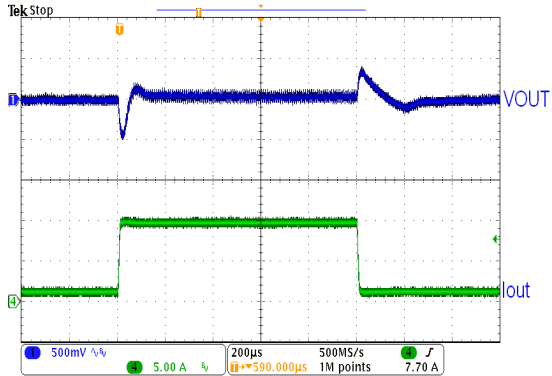
high side MOSFET peak current limit



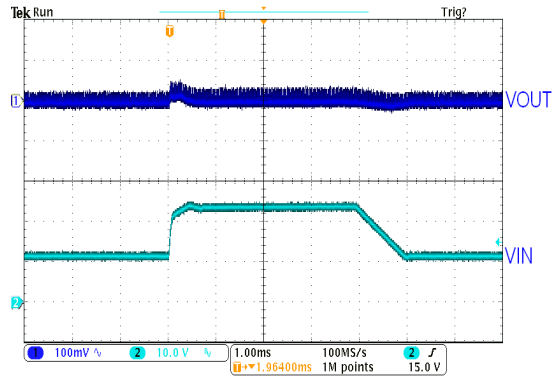
over voltage protection



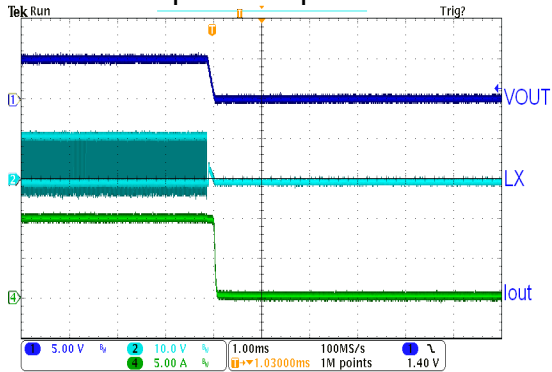
12Vin to 5Vout  
1A~9.6A load transient



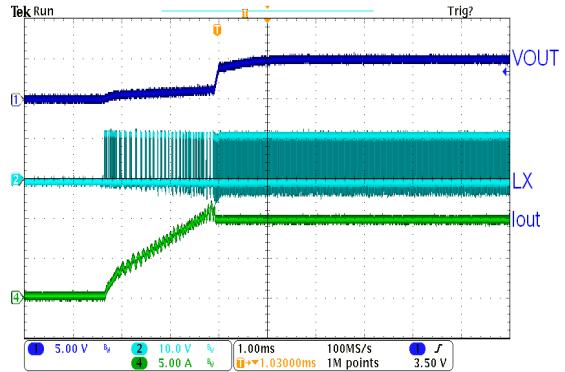
12Vin~24Vin line transient

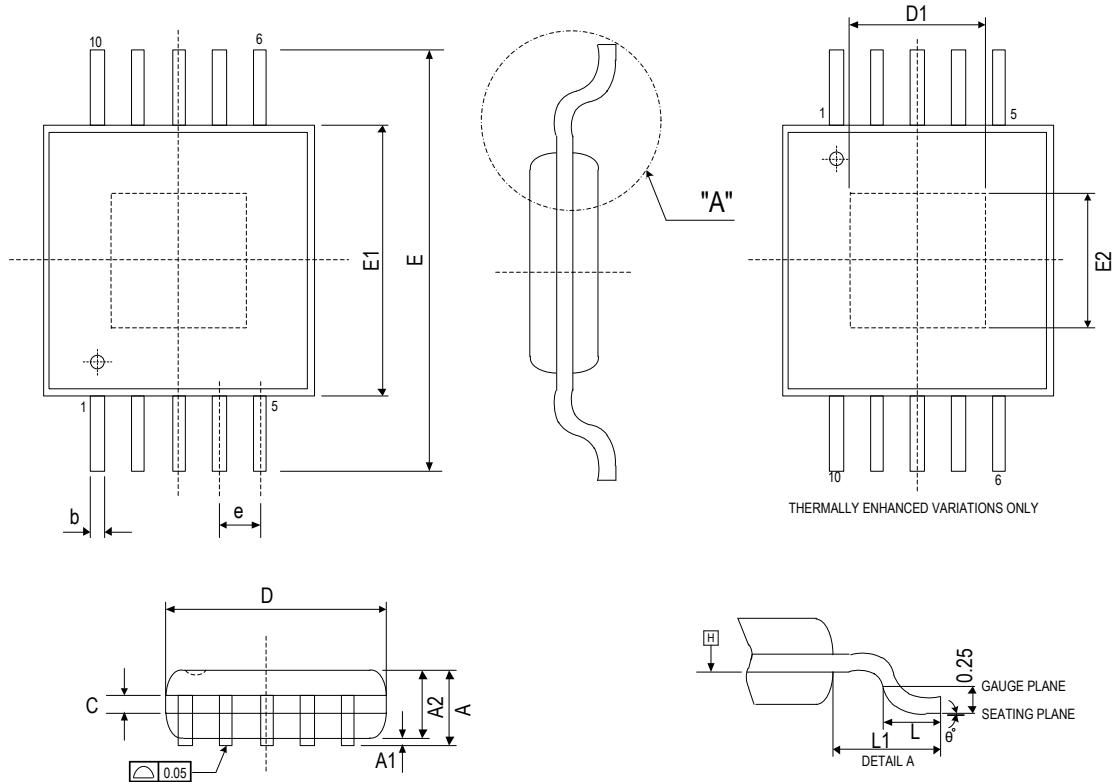


12Vin to 5Vout/9.6A load  
Over temperature protection



12Vin to 5Vout/9.6A load  
de-OTP re-start

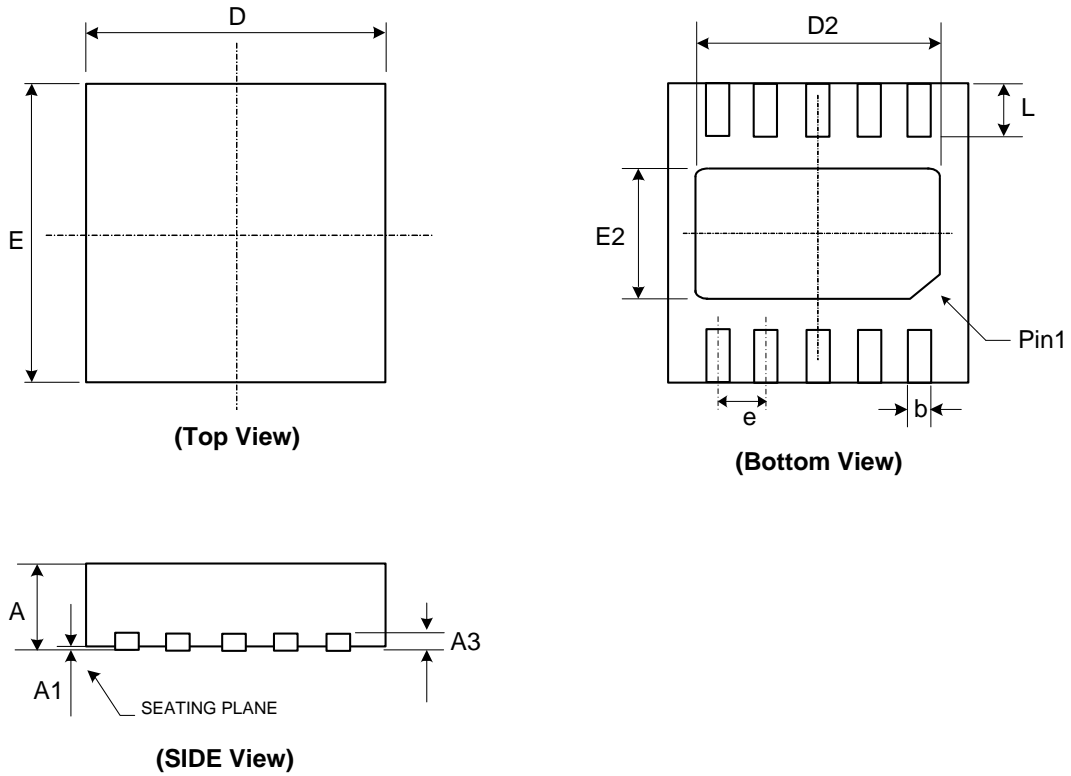


**❖ PACKAGE OUTLINES**
**(1) MSOP-10L-EP**


Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.1	-	-	0.043
A1	0	0.08	0.15	0	0.003	0.006
A2	0.75	0.85	0.95	0.03	0.034	0.038
C	0.08	0.15	0.23	0.003	0.006	0.009
D	2.9	3	3.1	0.114	0.118	0.122
D1	0.75	1.63	2.5	0.03	0.064	0.098
E	4.8	4.9	5	0.189	0.193	0.197
E1	2.9	3	3.1	0.114	0.118	0.122
E2	0.75	1.63	2.5	0.03	0.064	0.098
L	0.4	0.6	0.8	0.016	0.024	0.031
b	0.17	0.21	0.33	0.009	0.012	0.015
e	0.50 BSC			0.020 BSC		
y	-	-	0.1	-	-	0.004
θ	0°	-	8°	0°	-	8°

JEDEC outline: MO-187 BA-T

(2) TDFN-10L(3\*3)

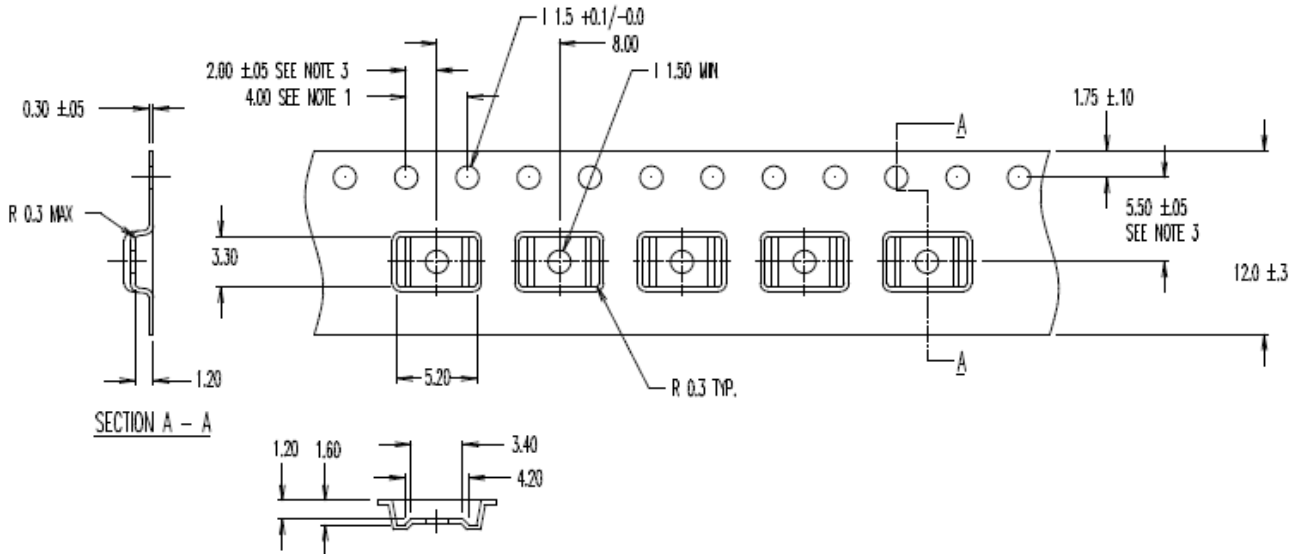


Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF.			0.008 REF.		
b	0.18	0.25	0.30	0.007	0.010	0.012
D	2.90	3.00	3.10	0.114	0.118	0.122
D2	2.20	2.40	2.50	0.087	0.094	0.098
E	2.90	3.00	3.10	0.114	0.118	0.122
E2	1.50	1.60	1.70	0.059	0.063	0.070
e	0.50 BSC.			0.020 BSC.		
L	0.30	0.40	0.50	0.012	0.016	0.020

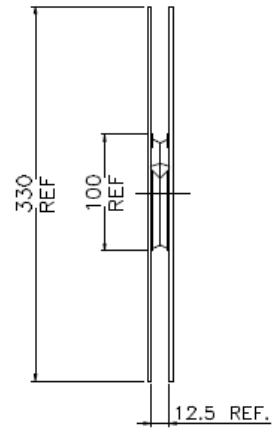
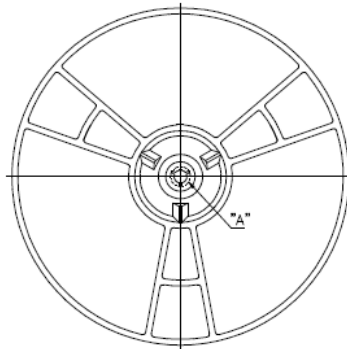
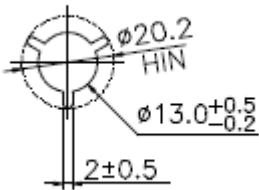
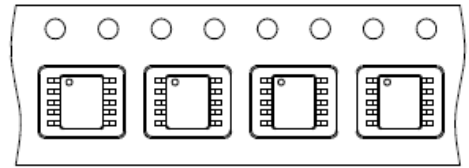
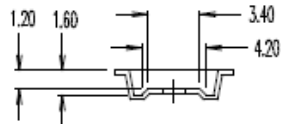


❖ Carrier tape dimension

(1)MSOP-10L-EP



SECTION A - A



(2)TDFN-10L(3\*3)

